

L Number	Hits	Search Text	DB	Time stamp
1	55667	EDTA	USPAT; US-PGPUB	2002/11/13 17:04
2	39361	barrier near4 layer	USPAT; US-PGPUB	2002/11/13 17:05
3	861606	tungsten W	USPAT; US-PGPUB	2002/11/13 17:05
4	233452	titanium Ti	USPAT; US-PGPUB	2002/11/13 17:05
5	83762	tantalum TA	USPAT; US-PGPUB	2002/11/13 17:05
6	16341	((titanium Ti) (tantalum TA)) adj (nitride N)	USPAT; US-PGPUB	2002/11/13 17:06
7	265	(tantalum TA) adj silicon adj nitride	USPAT; US-PGPUB	2002/11/13 17:07
8	9016	(barrier near4 layer) same ((tungsten W) (titanium Ti) (tantalum TA) (((titanium Ti) (tantalum TA)) adj (nitride N)) ((tantalum TA) adj silicon adj nitride))	USPAT; US-PGPUB	2002/11/13 17:08
9	142	((barrier near4 layer) same ((tungsten W) (titanium Ti) (tantalum TA) (((titanium Ti) (tantalum TA)) adj (nitride N)) ((tantalum TA) adj silicon adj nitride))) and EDTA	USPAT; US-PGPUB	2002/11/13 17:10
10	21271	electroplating	USPAT; US-PGPUB	2002/11/13 17:10
11	67	((barrier near4 layer) same ((tungsten W) (titanium Ti) (tantalum TA) (((titanium Ti) (tantalum TA)) adj (nitride N)) ((tantalum TA) adj silicon adj nitride))) and EDTA) and electroplating	USPAT; US-PGPUB	2002/11/13 19:02
12	808	nanometers same copper	USPAT; US-PGPUB	2002/11/13 18:49
13	152	(nanometers same copper) and electroplating	USPAT; US-PGPUB	2002/11/13 18:49
14	0	(barrier near4 layer) near2 bipyridyl	USPAT; US-PGPUB	2002/11/13 18:49
15	1524	bipyridyl	USPAT; US-PGPUB	2002/11/13 18:50
16	1	bipyridyl and ((nanometers same copper) and electroplating)	USPAT; US-PGPUB	2002/11/13 18:50
17	235	bipyridyl and EDTA	USPAT; US-PGPUB	2002/11/13 18:51
18	13	(bipyridyl and EDTA) and electroplating and copper	USPAT; US-PGPUB	2002/11/13 18:53
19	1	("6300244").PN.	USPAT; US-PGPUB	2002/11/13 18:55
20	0	("19 and 12").PN.	USPAT; US-PGPUB	2002/11/13 18:55
21	0	("19 and 15").PN.	USPAT; US-PGPUB	2002/11/13 18:55
22	1754	cyanide same ions	USPAT; US-PGPUB	2002/11/13 19:03
23	8	(cyanide same ions) and (((barrier near4 layer) same ((tungsten W) (titanium Ti) (tantalum TA) (((titanium Ti) (tantalum TA)) adj (nitride N)) ((tantalum TA) adj silicon adj nitride))) and EDTA) and electroplating)	USPAT; US-PGPUB	2002/11/13 19:03

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9	142	((barrier near4 layer) same ((tungsten W) (titanium Ti) (tantalum TA)) adj (nitride N)) ((tantalum TA) adj silicon adj nitride))) and EDTA	USPAT; US-PGPUB	2002/11/13 17:10
10	21271	electroplating	USPAT; US-PGPUB	2002/11/13 17:10
11	67	((((barrier near4 layer) same ((tungsten W) (titanium Ti) (tantalum TA) (((titanium Ti) (tantalum TA)) adj (nitride N)) ((tantalum TA) adj silicon adj nitride))) and EDTA) and electroplating	USPAT; US-PGPUB	2002/11/13 17:11